

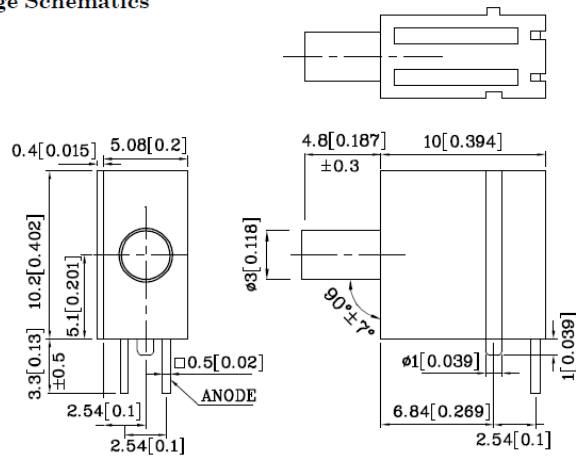
SE-B-31Y-ESD

Features

- Housing material: Type 66 Nylon
- Black casing provides superior contrast
- Housing UL rating: 94V-0
- Reliable & robust
- Custom color combinations available
- RoHS Compliant



Package Schematics



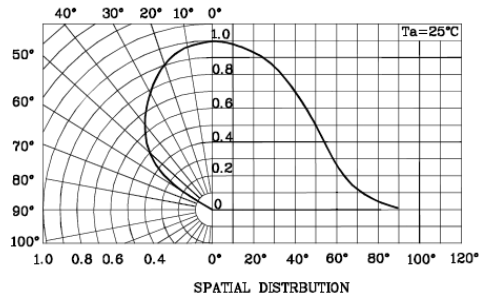
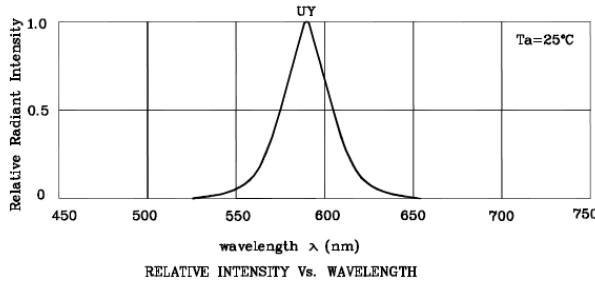
- Notes:
1. All dimensions are in millimeters (inches).
  2. Tolerance is ±0.25(0.01") unless otherwise noted.
  3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T <sub>A</sub> =25°C)		UY (GaAsP/GaP)	Unit
Reverse Voltage	V <sub>R</sub>	5	V
Forward Current	I <sub>F</sub>	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i <sub>FS</sub>	140	mA
Power Dissipation	P <sub>D</sub>	75	mW
Operating Temperature	T <sub>A</sub>	-40 ~ +85	°C
Storage Temperature	T <sub>stg</sub>	-40 ~ +85	
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds		
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds		

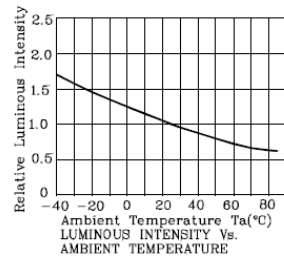
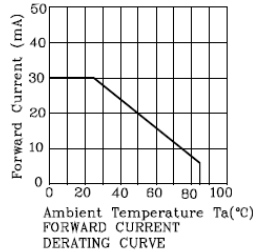
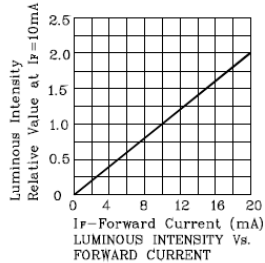
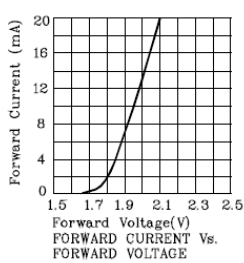
Operating Characteristics (T <sub>A</sub> =25°C)		UY (GaAsP/GaP)	Unit
Forward Voltage (Typ.) (I <sub>F</sub> =10mA)	V <sub>F</sub>	1.95	V
Forward Voltage (Max.) (I <sub>F</sub> =10mA)	V <sub>F</sub>	2.5	V
Reverse Current (Max.) (V <sub>R</sub> =5V)	I <sub>R</sub>	10	µA
Wavelength of Peak Emission (Typ.) (I <sub>F</sub> =10mA)	λ <sub>P</sub>	590	nm
Wavelength of Dominant Emission (Typ.) (I <sub>F</sub> =10mA)	λ <sub>D</sub>	588	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I <sub>F</sub> =10mA)	Δλ	35	nm
Capacitance (Typ.) (V <sub>F</sub> =0V, f=1MHz)	C	20	pF

Emitting Color	Emitting Material	Lens-color	Luminous Intensity (I <sub>F</sub> =10mA) mcd		Wavelength nm λ <sub>P</sub>	Viewing Angle 2θ 1/2
			min.	typ.		
Yellow	GaAsP/GaP	Yellow Diffused	2	3.8	590	100°

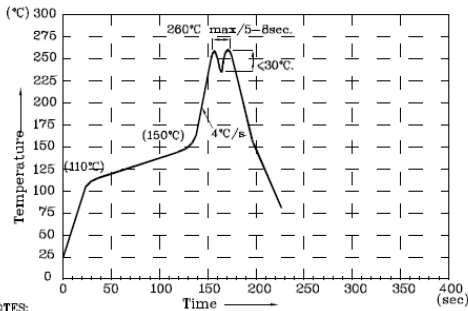
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❖ UY



Wave Soldering Profile for Thru-Hole Products (Pb-Free Components)



NOTES:

- 1.Recommend the wave temperature 245°C~260°C.The maximum soldering temperature should be less than 260°C.
- 2.Do not apply stress on epoxy resins when temperature is over 85°C.
- 3.The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
- 4.During wave soldering, the PCB top-surface temperature should be kept below 105°C.
- 5.No more than once.

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity / Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.